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Douglas Burleigh
Gregory R. Stockton
Editors

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Introduction

After having been in Orlando for 25 years, Thermosense has now moved to Baltimore. The change in venue has resulted in a slightly larger audience for the conference and the number of vendors in the exhibition hall was considerably larger in 2012. And since Thermosense is no longer tied to Easter, traveling will be easier.

In 2012 significant developments in Infrared imaging equipment were seen. Developments include scanners IR cameras with focal plane array (FPA) detectors as large as 1000x1000, which have improved sensitivity and faster scan rates than ever before. Prototypes of 2000x2000 FPA's were being shown at the exhibit this year.

Also, in recent years, low cost IR cameras have become available from several manufacturers. It's now possible to buy a low resolution IR camera for as little as \$3K. This can make IR technology available to more users for more applications. Unfortunately, this can also put IR cameras in the hands of untrained operators who may incorrectly collect or interpret IR data. And this can reflect poorly on the IR field.

It is a challenge for those of us who have been involved in IR for many years to prevent the use of IR cameras by operators with insufficient training or guidance.

The use of thermography for preventive maintenance (PM) and nondestructive testing (NDT) is becoming more accepted and even required. Thermography has been shown to provide valuable information which has been previously difficult or impossible to obtain. It may provide unique solutions to problems which previously had none. The demonstrated uses of thermography are numerous. The number of future applications is virtually infinite.

The Thermosense conference has played a significant role in the development of thermographic applications and equipment. It has been an important forum which annually unites researchers and practical users of thermography for a sharing of ideas and experiences.

This year's Thermosense conference includes papers from Austria, Brazil, Canada, Chile, China, Finland, France, Greece, India, Italy, Japan, Korea, Poland, Russia, Spain, and the United States, with attendees from additional countries, making it a truly international conference.

**Douglas Burleigh
Gregory R. Stockton**